Assembly Glue 305.0

High quality synthetic resin dispersion glue for universal application

Fields of application
- Assembly bonding
- Frame bonding
- Bonding of laminates
- Bonding in high frequency fields
- Core production
- Veneer joint bonding
- Joint and frame bonding of hard and soft textured woods

Advantages
- High green strength, therefore short pressing times possible
- Favourable open time
- Short setting times with cold and hot bonding
- Good application properties with machines and hand-gluing devices

Properties of the bond
- Good moisture resistance according to DIN EN 204, bond quality D2
  (test no. 505 20968 M dated 14.08.1998 from “Fensterinstitut Rosenheim”)
- Very high bond strength according to DIN/EN 205
- Tough-elastic glue film that gives a good tool life

Properties of the glue
- Base: PVAC dispersion
- Specific gravity: approx. 1.20 g/cm³
- PH-value: approx. 7
- Colour: beige
- Viscosity at 20°C: 10,000 ± 2,000 mPa s
- Brookfield RVT spindle 6/20 rpm: medium viscosity, good processing properties
- Consistency: approx. 10 minutes
- Chalk point: +5°C
- Open time: approx. 10 minutes
- Identification: not required according to the German hazardous substances regulations GefStoffV (see our safety data sheet)

Application methods
- With brush and toothed spatula
- With manual gluing devices (e.g. pressure chamber and pistol)
- With glue spreading machines (2- and 4-roller-systems)

Application techniques
The materials to be bonded must be dry, free from dust, oil and grease and acclimatised.
Moisture content of the wood 8-12 %.
The most favourable processing temperature is at 18-20°C.
Do not process below +10°C.
KLEIBERIT Assembly Glue 305.0 is ready to use.
Thinning and addition of fillers alter the glue.

Application quantity:
- 100-150 g/m² when applied with machine
- 150-200 g/m² when applied with manual gluing device

Open time: approx. 10 minutes
The open time is influenced by the quantity applied, the absorption properties of the substrates, the moisture content of the wood, the humidity of the air and the temperature.

Pressure: min. 0.3 N/mm²

Pressing times:

<table>
<thead>
<tr>
<th>Application</th>
<th>Temp.</th>
<th>Press Time</th>
</tr>
</thead>
<tbody>
<tr>
<td>board joint bonding</td>
<td>20°C</td>
<td>8-12 min.</td>
</tr>
<tr>
<td>board joint bonding</td>
<td>80°C</td>
<td>3- 5 min.</td>
</tr>
<tr>
<td>(preheated on one side)</td>
<td></td>
<td></td>
</tr>
<tr>
<td>board joint bonding</td>
<td></td>
<td></td>
</tr>
<tr>
<td>(in high frequency field)</td>
<td></td>
<td>20-25 sec.</td>
</tr>
<tr>
<td>bonding of structural</td>
<td>20°C</td>
<td>10-12 min.</td>
</tr>
<tr>
<td>components</td>
<td></td>
<td></td>
</tr>
<tr>
<td>veneer bonding</td>
<td>20°C</td>
<td>12-15 min.</td>
</tr>
<tr>
<td>veneer bonding</td>
<td>80°C</td>
<td>3- 5 min.</td>
</tr>
<tr>
<td>surface bonding (HPL-boards)</td>
<td>20°C</td>
<td>20-25 min.</td>
</tr>
<tr>
<td>surface bonding (HPL-boards)</td>
<td>50°C</td>
<td>8-10 min.</td>
</tr>
</tbody>
</table>

These guidelines are given without obligation; they are based on bonding wood with a 10 % moisture content. As the different bonding processes are influenced by various factors, exact times must be determined by own trials to be carried out in your factory.

Page 1 of 2
Assembly Glue 305.0

Cleaning
Machines, applicators and adhesive containers can be cleaned with water.

Packaging
KLEIBERIT Assembly Glue 305.0:
• carton of 12 squeeze bottles, 500 g net each
• plastic pail, 10 kg net
• plastic pail, 33 kg net
• other sizes on request

Storage
KLEIBERIT Assembly Glue 305.0 can be stored in factory-sealed containers at a temperature of 20°C for approx. 1 year. The frost resistance during transport is -15°C.
Bring carefully up to room temperature (20°C) and stir before use.

EX1109; replaces previous versions